



Features

- High isolation 5000 VRMS
- Patented coplanar structure DMC-Isolator®
- DC input with transistor output
- Operating Temperature range 55 °C to 110 °C
- External Creepage ≥ 7.4mm
- Distance Through Isolation ≥ 0.4mm
- Spatial Distance ≥ 7.5mm (S/SL Type)
- Spatial Distance ≥ 8.0mm (M/SLM Type)
- RoHS and REACH Compliance
- Halogen Free Compliance (Optional)
- MSL class 1
- Regulatory Approvals
 - ✓ UL UL1577 (E364000)
 - ✓ VDE EN60747-5-5(VDE0884-5)
 - ✓ CQC GB4943.1, GB8898 (14001104781)
 - ✓ IEC62368 (FI/41119)

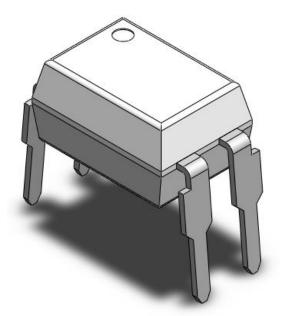
Description

The CT851 series consists of a high power transistor optically coupled to an Infrared-emitting diode in a 4-lead DMC-Isolator® package with different lead forming options.

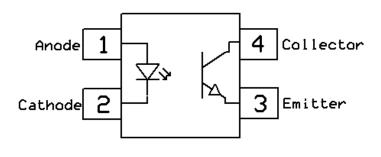
Applications

- Switch mode power supplies
- Computer peripheral interface
- Microprocessor system interface

Package Outline



Schematic



Note: Different lead forming options available. See package dimension.



Absolute Maximum Ratings $T_A = 25^{\circ}C$, unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Ratings	Units	Notes
Viso	Isolation voltage (AC, 1 minute, 40 ~ 60% R.H.)	5000	V _{RMS}	
Ртот	Total power dissipation	260	mW	
Topr	Operating temperature	-55 ~ +100	°C	
Тѕтс	Storage temperature	-55 ~ + 150	°C	
TsoL	С	260	°C	
Emitter				
l _F	Forward current	60	mA	
I _{F(TRANS)}	Peak transient current (Duty cyc 50%, pulse width<500ms)	100	mA	
I _{F(TRANS)}	Peak transient current (≤1µs P.W,300pps)	1	А	
V_{R}	Reverse voltage	6	V	
P _D	Power dissipation	150	mW	
Detector				
P _D	Power dissipation	300	mW	
B _{VCEO}	Collector-Emitter Breakdown Voltage	350	V	
B _{VECO}	Emitter-Collector Breakdown Voltage	7	V	
lc	Collector Current	100	mA	

Note:

1. When plan operating current IF condition, the IC current limit must be considered.



Electrical Characteristics $T_A = 25$ °C (unless otherwise specified)

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I _F =10mA	-	1.2	1.4	V	
I _R	Reverse Current	V _R = 6V	-	-	5	μΑ	
Cin	Input Capacitance	f= 1MHz	-	30	-	pF	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
B _{VCEO}	Collector-Emitter Breakdown	I _C = 0.1mA	350	-	-	V	
Bveco	Emitter-Collector Breakdown	I _E = 0.1mA	7	-	-	V	
ICEO	Collector-Emitter Dark Current	V _{CE} = 200V, I _F =0mA	-	-	100	nA	

Transfer Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Мах	Units	Notes
CTR	Current Transfer Ratio	I _F = 5mA, V _{CE} = 5V	50	-	600	%	
Variour	Collector-Emitter Saturation Vce(SAT) IF= 20mA, Ic= 1mA		_		0.4	V	
VCE(SAT)	Voltage	IF= ZUITA, IC= TITIA	-	-	0.4	V	
Rio	Isolation Resistance	Vio= 500VDC	5x10 ¹⁰	-	-	Ω	
C _{IO}	Isolation Capacitance	f= 1MHz	-	10	-	pF	

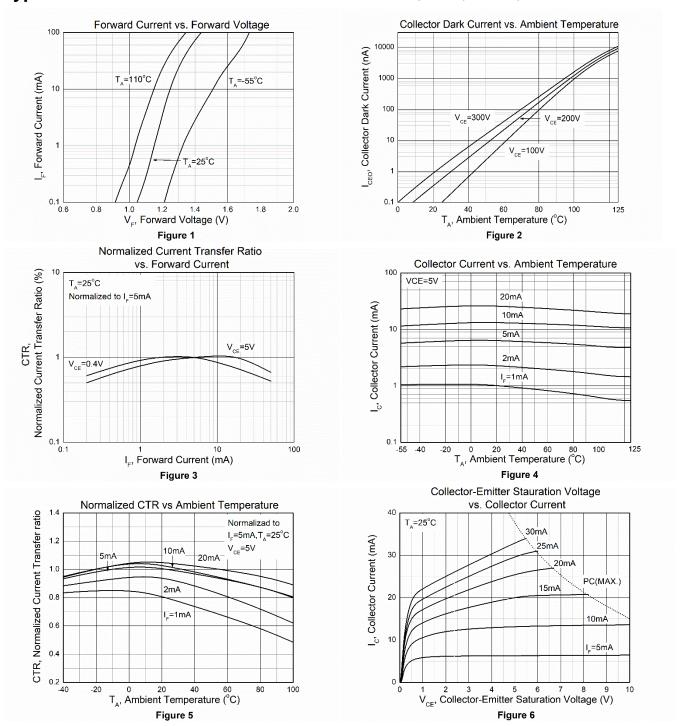
Switching Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
t _r	Rise Time	L- 2m/ V 2V B- 1000	-	6	18	0	
tf	Fall Time	I_{C} = 2mA, V_{CE} = 2V, R_{L} = 100 Ω	-	8	18	μS	





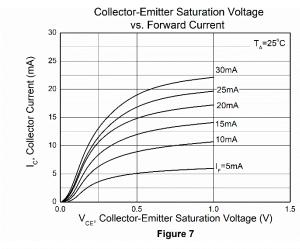
Typical Characteristic Curves $T_A = 25$ °C, unless otherwise specified (Continued)

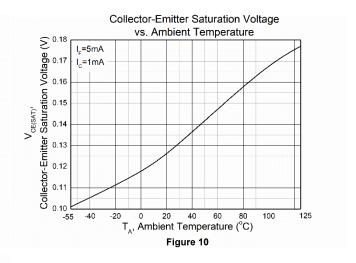


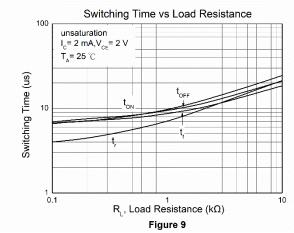




Typical Characteristic Curves $T_A = 25$ °C, unless otherwise specified (Continued)









Test Circuit

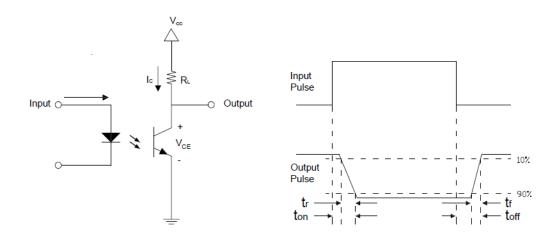
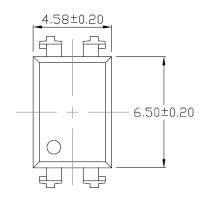


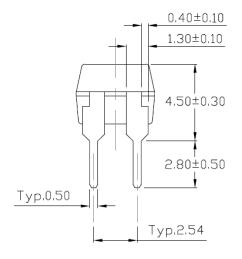
Figure 11: Switching Time Test Circuits

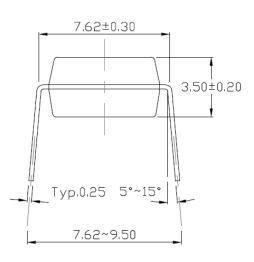


Package Dimension Dimensions in mm unless otherwise stated

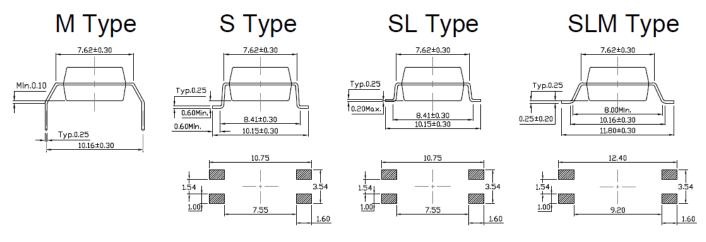
Standard DIP - Through Hole







Forming Option







Marking Information



Note:

CT : Denotes "CT Micro"

851 : Part Number

V : VDE Safety Mark Option (Blank or V)

Y : One Digit Year CodeWW : Two Digit Work WeekK : Manufacturing Code

Ordering Information

CT851 (V)(Y)(Z)

CT = Denotes "CT Micro"

851 = Part Number

V = VDE Safety Mark Option (Blank or V)

Y = Lead Form Option (S, SL, M, SLM or Blank)

Z = Tape and Reel Option (Blank, T1 or T2)

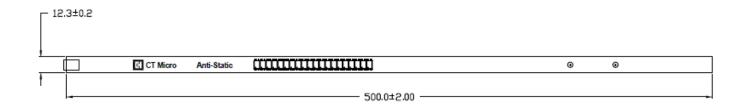
G = Material Option (G: Halogen Free, Blank: Non-Halogen Free)

Option	Description	Quantity
None	Standard 4 Pin Dip	100 Units/Tube
М	M Gullwing (400mil) Lead Forming	
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1500 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1500 Units/Reel
SL(T1)	SL(T1) Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	
SL(T2)	Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	1500 Units/Reel
SLM(T1)	Surface Mount (Gullwing) Lead Forming– With Option 1 Taping	1500 Units/Reel
SLM(T2) Surface Mount (Gullwing) Lead Forming – With Option 2 Taping		1500 Units/Reel

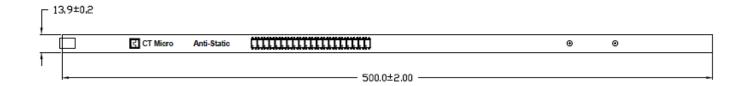


Carrier Specifications Dimensions in mm unless otherwise stated

Tube Option Standard DIP



Tube Option M Type

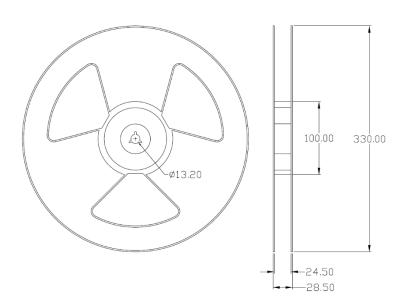


Reel Dimension All dimensions are in mm, unless otherwise stated

Option S(T1/T2) & SL(T1/T2)

100.00 330.00 Ø13.20 -16.50 -20.50

Option SLM(T1/T2)



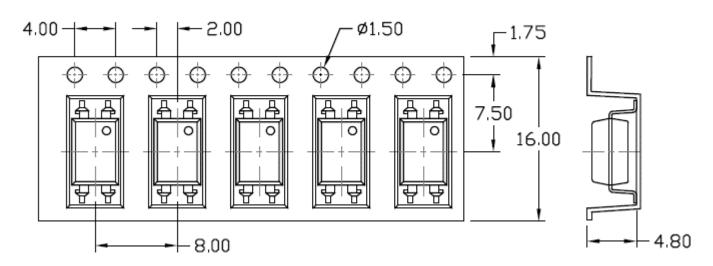




Carrier Tape Specifications Dimensions in mm unless otherwise stated

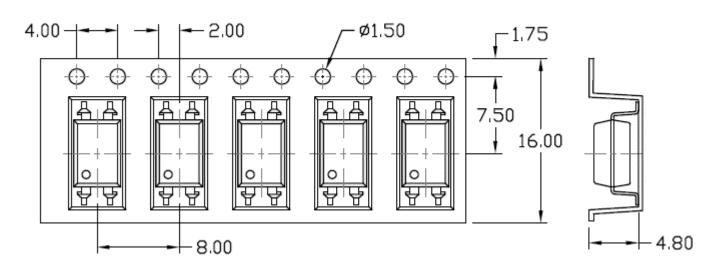
Option S(T1) & SL(T1)

Input Direction



Option S(T2) & SL(T2)

Input Direction

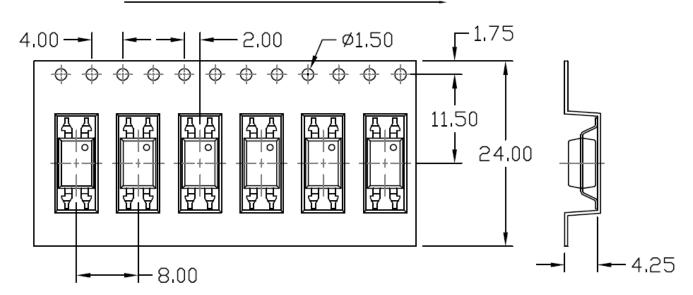






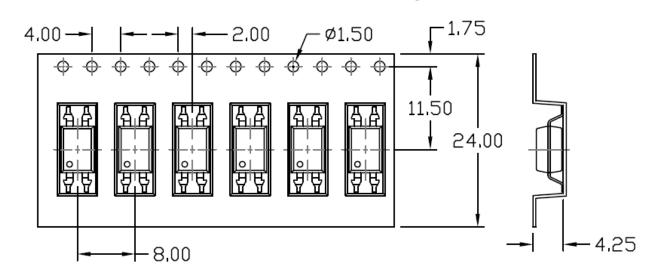
Option SLM(T1)

Input Direction



Option SLM(T2)

Input Direction





Solderability spec (Follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

Wave soldering (Follow the JEDEC standard JESD22-A111)

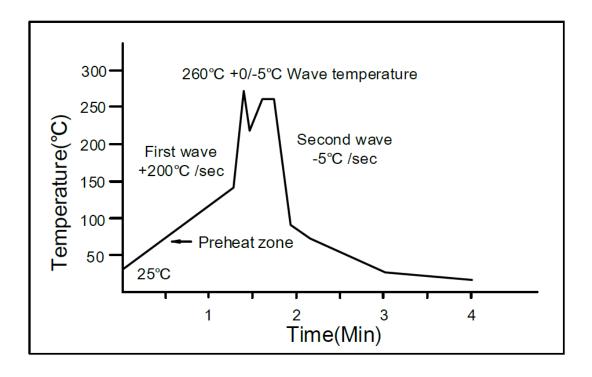
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature: 25 to 140°C.

Preheat time: 30 to 80 sec.



Iron soldering (Follow the standard MIL-STD 202G, Method 210F)

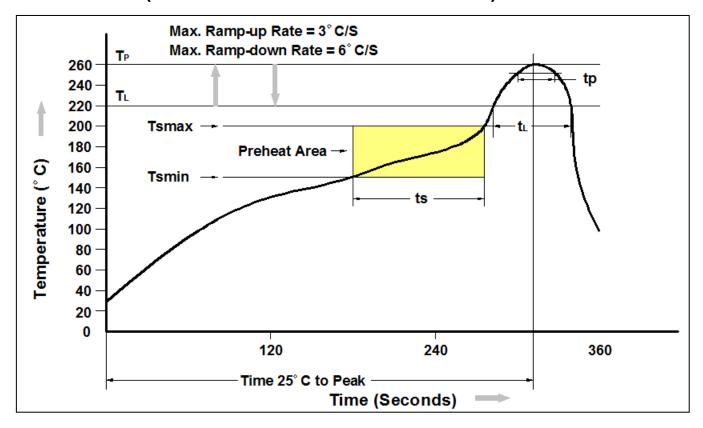
Allow single lead soldering in every single process.

One time soldering is recommended. Temperature: 350±10°C

Time: 5 sec max.



Reflow Profile (Follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t⊳)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



CT851 Series

DC Input 4-Pin DMC-Isolator® High BVceo Phototransistor Optocoupler

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